



FDMS8460

N-Channel Power Trench[®] MOSFET

40V, 49A, 2.2mΩ

Features

- Max $r_{DS(on)}$ = 2.2mΩ at $V_{GS} = 10V, I_D = 25A$
- Max $r_{DS(on)}$ = 3.0mΩ at $V_{GS} = 4.5V, I_D = 21.7A$
- Advanced Package and Silicon combination for low $r_{DS(on)}$
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

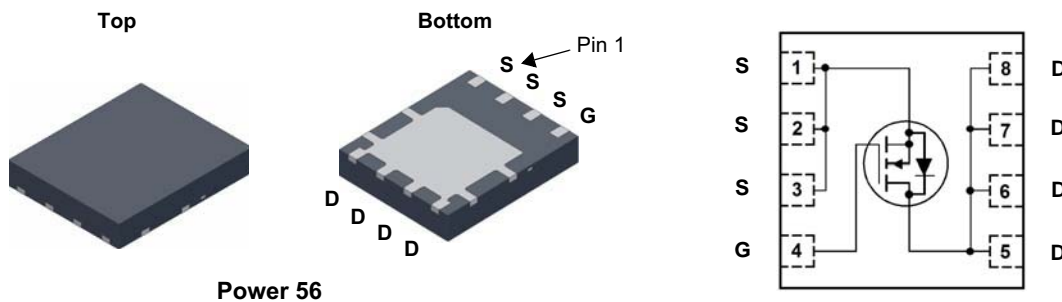


General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench[®] process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Application

- DC - DC Conversion



MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rated	Units
V_{DS}	Drain to Source Voltage	40	V
V_{GS}	Gate to Source Voltage	± 20	V
I_D	Drain Current -Continuous (Package limited) $T_C = 25^\circ\text{C}$	49	A
	-Continuous (Silicon limited) $T_C = 25^\circ\text{C}$	167	
	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	25	
	-Pulsed	160	
E_{AS}	Single Pulse Avalanche Energy (Note 3)	864	mJ
P_D	Power Dissipation $T_C = 25^\circ\text{C}$	104	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	2.5	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.2	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS8460	FDMS8460	Power 56	13"	12 mm	3000 units

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, referenced to 25°C		32		$\text{mV}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0\text{V}, V_{DS} = 32\text{V}$,			1	μA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			± 100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	1.0	1.9	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, referenced to 25°C		-7.5		$\text{mV}/^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}, I_D = 25\text{A}$		2.0	2.2	m Ω
		$V_{GS} = 4.5\text{V}, I_D = 21.7\text{A}$		2.6	3.0	
		$V_{GS} = 10\text{V}, I_D = 25\text{A}, T_J = 125^\circ\text{C}$		2.6	3.3	
g_{FS}	Forward Transconductance	$V_{DD} = 5\text{V}, I_D = 25\text{A}$		137		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$, $f = 1\text{MHz}$		5415	7205	pF
C_{oss}	Output Capacitance			1470	1955	pF
C_{rss}	Reverse Transfer Capacitance			170	250	pF
R_g	Gate Resistance	$f = 1\text{MHz}$	0.1	1.4	3.1	Ω

Switching Characteristics

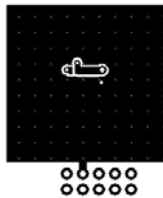
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 20\text{V}, I_D = 25\text{A}$, $V_{GS} = 10\text{V}, R_{GEN} = 6\Omega$		19	35	ns	
t_r	Rise Time			9	19	ns	
$t_{d(off)}$	Turn-Off Delay Time			48	78	ns	
t_f	Fall Time			7	14	ns	
Q_g	Total Gate Charge		$V_{GS} = 0\text{V to } 10\text{V}$		78	110	nC
Q_g	Total Gate Charge	$V_{GS} = 0\text{V to } 4.5\text{V}$	$V_{DD} = 20\text{V}$, $I_D = 25\text{A}$		36	51	nC
Q_{gs}	Gate to Source Charge				15		nC
Q_{gd}	Gate to Drain "Miller" Charge				10		nC

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 25\text{A}$ (Note 2)		0.8	1.3	V
		$V_{GS} = 0\text{V}, I_S = 2.1\text{A}$ (Note 2)		0.7	1.2	
t_{rr}	Reverse Recovery Time	$I_F = 25\text{A}, di/dt = 100\text{A}/\mu\text{s}$		53	85	ns
Q_{rr}	Reverse Recovery Charge			40	64	nC

NOTES:

- $R_{\theta JA}$ is determined with the device mounted on a 1in^2 pad 2 oz copper pad on a $1.5 \times 1.5\text{in}$. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. $50^\circ\text{C}/\text{W}$ when mounted on a 1in^2 pad of 2 oz copper.



b. $125^\circ\text{C}/\text{W}$ when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width $< 300\mu\text{s}$, Duty cycle $< 2.0\%$.

3. Starting $T_J = 25^\circ\text{C}$, $L = 3\text{mH}$, $I_{AS} = 24\text{A}$, $V_{DD} = 40\text{V}$, $V_{GS} = 10\text{V}$

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

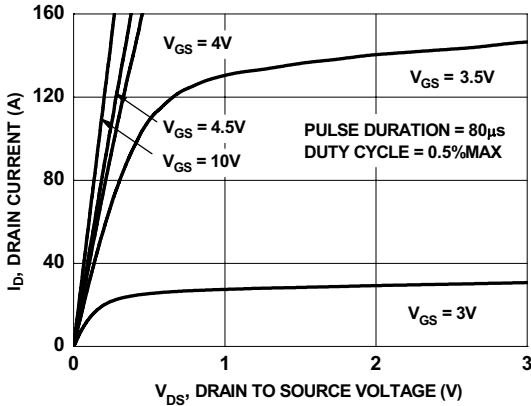


Figure 1. On-Region Characteristics

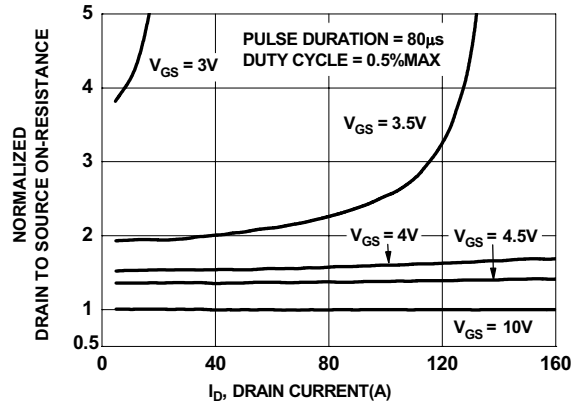


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

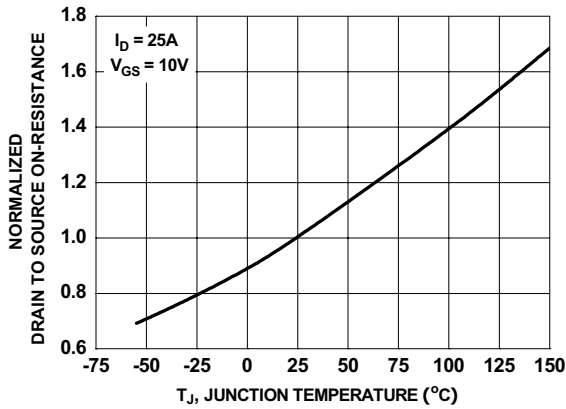


Figure 3. Normalized On-Resistance vs Junction Temperature

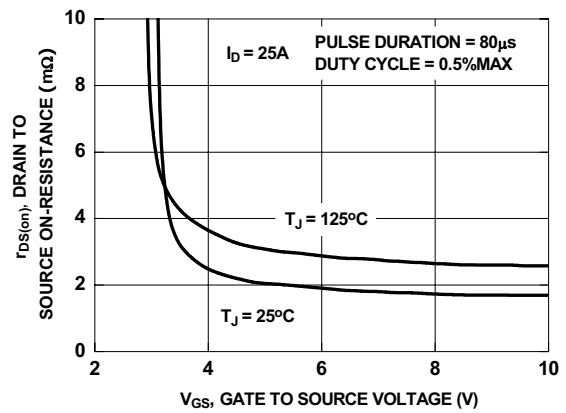


Figure 4. On-Resistance vs Gate to Source Voltage

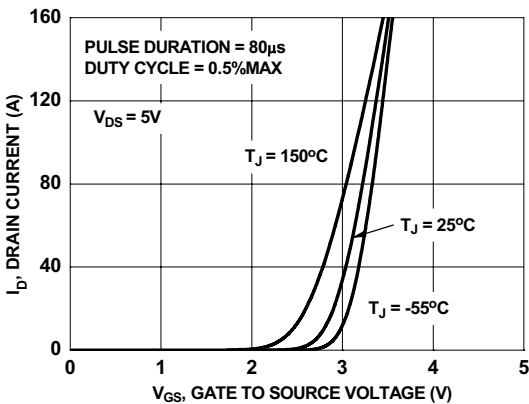


Figure 5. Transfer Characteristics

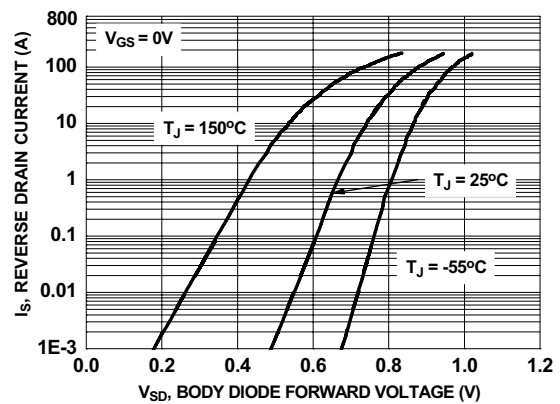


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

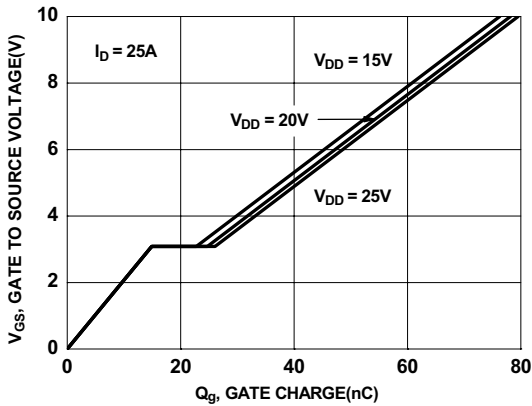


Figure 7. Gate Charge Characteristics

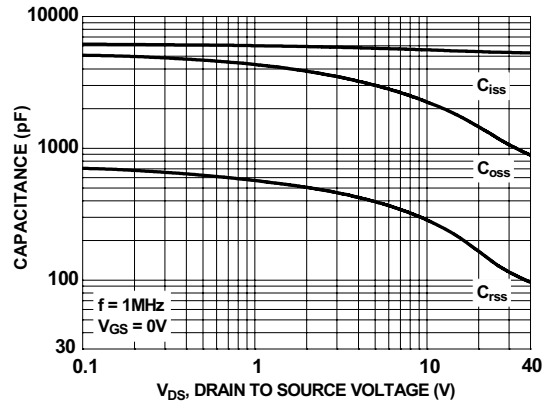


Figure 8. Capacitance vs Drain to Source Voltage

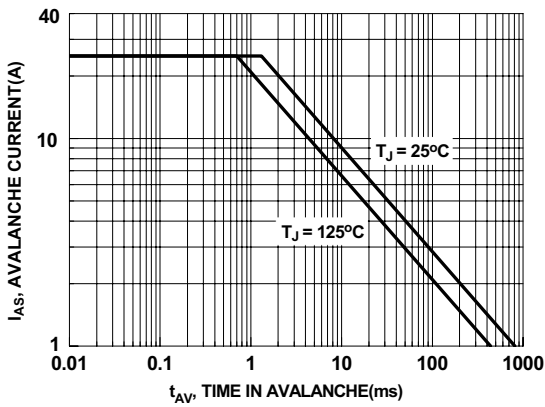


Figure 9. Unclamped Inductive Switching Capability

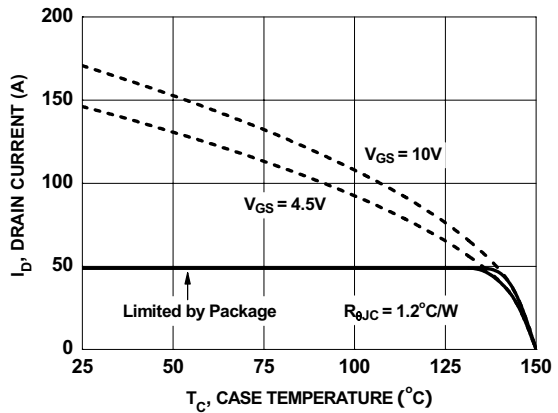


Figure 10. Maximum Continuous Drain Current vs Case Temperature

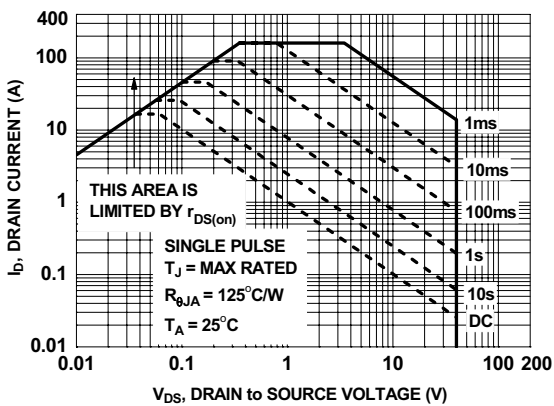


Figure 11. Forward Bias Safe Operating Area

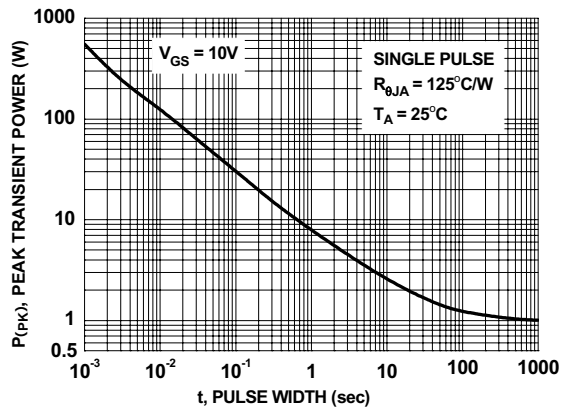


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

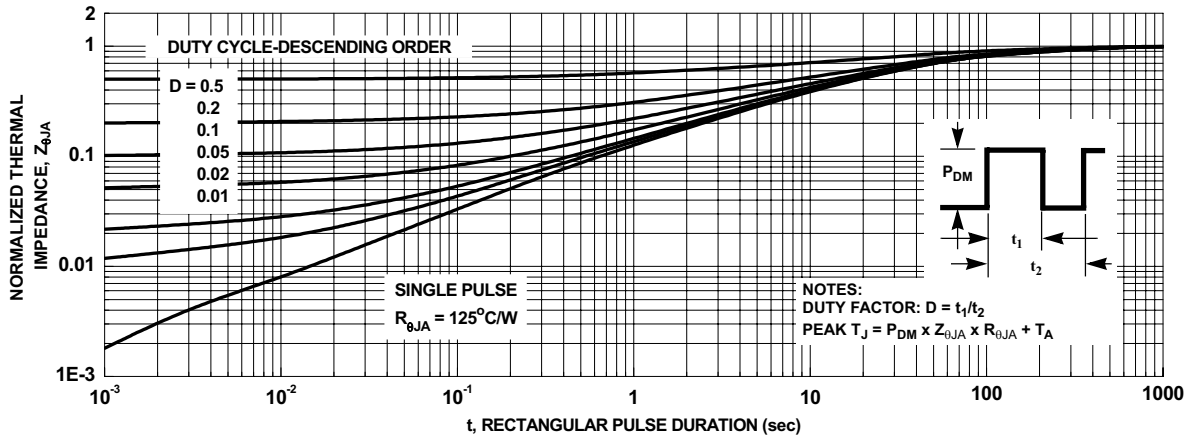
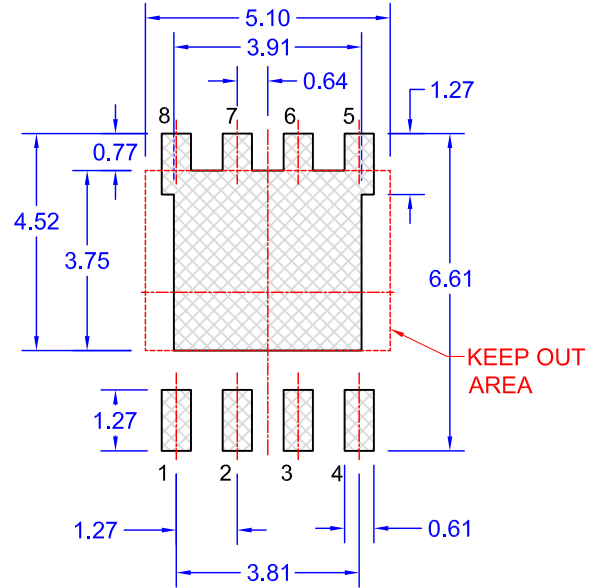


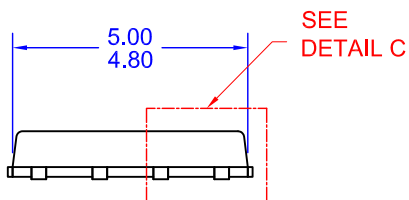
Figure 13. Transient Thermal Response Curve



TOP VIEW

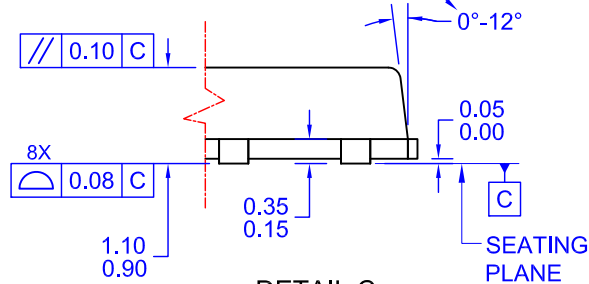


LAND PATTERN RECOMMENDATION

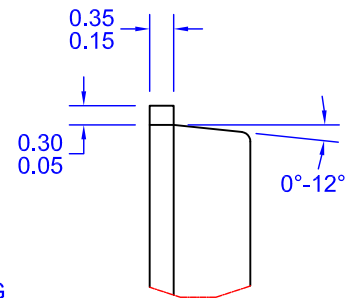


SIDE VIEW

OPTIONAL DRAFT ANGLE MAY APPEAR ON FOUR SIDES OF THE PACKAGE



DETAIL C
SCALE: 2:1



DETAIL B
SCALE: 2:1



BOTTOM VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- A. PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. AA, DATED OCTOBER 2002.
- B. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- E. IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.
- F. DRAWING FILE NAME: PQFN08AREV10



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